

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,056,766 B2
APPLICATION NO. : 10/731831
DATED : June 6, 2006
INVENTOR(S) : Hei Ming Shiu

Page 1 of 1

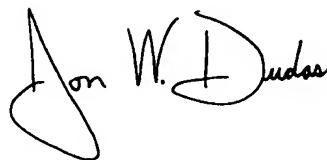
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In Column 7, Line 11, Claim No. 14:
Change "dice, comprising" to --die, comprising--
In Column 7, Line 18, Claim No. 14:
Change "dice to the mold" to --die to the mold--
In Column 7, Line 19, Claim No. 14:
Change "of the dice have" to --of the die have--
In Column 7, Line 22, Claim No. 14:
Change "of the dice to" to --of the die to--
In Column 7, Line 24, Claim No. 14:
Change "dice;" to --die;--
In Column 7, Line 25, Claim No. 14:
Change "encapsulating the dice," to --encapsulating the die,--
In Column 7, Line 28, Claim No. 14:
Change "such that a bottom" to --such that bottom--
In Column 7, Line 30, Claim No. 14:
Change "encapsulated dice to" to --encapsulated die to--
In Column 8, Line 14, Claim No. 20:
Change "wherein the dice" to --wherein the die--
In Column 8, Line 15, Claim No. 20:
Change "side of the dice" to --side of the die--

This certificate supersedes the Certificate of Correction issued May 20, 2008.

Signed and Sealed this

Seventeenth Day of June, 2008



JON W. DUDAS
Director of the United States Patent and Trademark Office